

Module Assembly Adhesives

Product Name	Description	Key Attributes	Glass Transition Temperature, Tg (°C)	Coefficient of Thermal Expansion, CTE (ppm/°C)		Viscosity at 25°C (cP)	Modulus at 25°C (MPa)	Recommended Cure
				Below Tg	Above Tg			
UV + Thermal Cure								
LOCTITE 3217	Acrylated epoxy adhesive	 Designed for image sensor module assemblies and temperature sensitive electronics components Fast cure at low temperatures 	82	53	178	37,600	2,865	1 sec. at 100 mW/cm² + 30 min. at 60°C
LOCTITE ABLESTIK NCA 2200	Acrylated epoxy adhesive	 One component Low viscosity Fast cure at low temperatures Good adhesion to a variety of substrates Designed for image sensor module assemblies and temperature sensitive electronics components 	97	43	150	9,000	5,000	2 sec. at 100 mW/cm² + 30 min. at 80°C
LOCTITE ABLESTIK NCA 2280	Acrylated epoxy adhesive	 One component High thixotropic index High viscosity Black in color to prevent light penetration Fast cure at low temperatures Good adhesion to liquid crystal polymer (LCP) substrates Designed for image sensor module assemblies and temperature sensitive electronics components 	90	45	156	54,000	4,500	2 sec. at 100 mW/cm² + 30 min. at 80°C
LOCTITE ABLESTIK NCA 2280LV	Acrylated epoxy adhesive	 One component High thixotropic index Fast cure at low temperatures Low transmittance Good adhesion to liquid crystal polymer (LCP) substrates Black in color to prevent light penetration Designed for image sensor module assemblies and temperature sensitive electronics components 	75	54	160	32,800	3,000	2 sec. at 100 mW/cm² + 30 min. at 80°C

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